

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): A method for manufacturing hollow ceramics fibers with the pores of the micron-scale hollow structure unidirectionally oriented, comprising the steps of:

dispersing organic fibers in a dielectric liquid and applying a high voltage to the dielectric liquid containing said organic fibers dispersed to electrostatically align said organic fibers and to produce a fiber accumulation of unidirectionally-oriented organic fibers,

using the fiber accumulation as a mold and dipping the same in a ceramics base solution, and then

removing the mold by treatment with heat or an organic solvent to form hollow ceramic fibers.

Claim 2 (Currently Amended): The method of ~~manufacturing hollow ceramics fibers unidirectionally oriented according to~~ Claim 1, wherein the organic fiber is at least one selected from the group consisting of raw silk, cotton, hemp, nylon, polyester, acrylic, cellulose and chitin.

Claim 3 (Currently Amended): The method for ~~manufacturing hollow ceramics fibers unidirectionally oriented according to~~ of Claim 1, wherein the ceramics base solution is composed of an comprises at least one alkoxide or chloride of titanium, aluminum, zirconium or silicon, and alcohol, and optionally water, or hydrochloric acid.

Claim 4 (Currently Amended): The method for ~~manufacturing hollow ceramics fibers unidirectionally oriented according to~~ of Claim 1, wherein the ceramics base solution is

~~composed of comprises~~ polyethylene glycol, surfactant(s) and organic polymer(s) represented by block copolymer, in addition to ~~an~~ at least one alkoxide or chloride of titanium, aluminum, zirconium or silicon, and alcohol, and optionally water, or hydrochloric acid.

Claim 5 (Currently Amended): The method ~~for manufacturing hollow ceramics fibers unidirectionally oriented according to~~ of Claim 1, wherein dipping is performed by the dip coating, dipping or spin coating method.

Claim 6 (Currently Amended): The method ~~for manufacturing hollow ceramics fibers unidirectionally oriented according to~~ of Claim 1, wherein the mold is removed by treatment with heat or an organic solvent.

Claim 7 (New): The method of Claim 1, wherein the organic fiber is raw silk.

Claim 8 (New): The method of Claim 1, wherein the organic fiber is cotton.

Claim 9 (New): The method of Claim 1, wherein the organic fiber is hemp.

Claim 10 (New): The method of Claim 1, wherein the organic fiber is nylon.

Claim 11 (New): The method of Claim 1, wherein the organic fiber is polyester.

Claim 12 (New): The method of Claim 1, wherein the organic fiber is acrylic.

Claim 13 (New): The method of Claim 1, wherein the organic fiber is cellulose.

Claim 14 (New): The method of Claim 1, wherein the organic fiber is chitin.

Claim 15 (New): The method of Claim 1, wherein the dielectric liquid is selected from the group consisting of carbon tetrachloride, n-hexane, cyclohexane, and fluorine and chlorine substituted carbon.

Claim 16 (New): The method of Claim 1, wherein a voltage ranging from about 15 kV/1-2cm is applied.

Claim 17 (New): The method of Claim 1, wherein said ceramics base solution comprises an alkoxide or chloride of titanium.

Claim 18 (New): The method of Claim 1, wherein said ceramics base solution comprises an alkoxide or chloride of aluminum.

Claim 19 (New): The method of Claim 1, wherein said ceramics base solution comprises an alkoxide or chloride of zirconium.

Claim 20 (New): The method of Claim 1, wherein said ceramics base solution comprises an alkoxide or chloride of silicon.

Claim 21 (New): The method of Claim 1, wherein the ceramics base solution further comprises an organic polymer.

Claim 22 (New): The method of Claim 1, wherein the ceramics base solution further comprises polyethylene glycol.

Claim 23 (New): The method of Claim 1, wherein the ceramics base solution further comprises a surfactant or an organic block polymer.

Claim 24 (New): The method of Claim 1, wherein the ceramics base solution further comprises cetyltrimethyl ammonium chloride, hexadecyltrimethyl ammonium bromide, Pluronic E127 or Pluronic P123.

Claim 25 (New): The method of Claim 1, wherein the mold is removed by a heat treatment.

Claim 26 (New): The method of Claim 1, wherein the mold is removed by a heat treatment at a temperature ranging from 300-700°C.

Claim 27 (New): The method of Claim 1, wherein the mold is removed by treatment with hydrochloric acid.

Claim 28 (New): The method of Claim 1, wherein the mold is removed by treatment with sulfuric acid.

Claim 29 (New): The method of Claim 1, wherein the mold is removed by treatment with nitric acid.

Claim 30 (New): The method of Claim 1, wherein the mold is removed by treatment with formic acid.

Claim 31 (New): The method of Claim 1, wherein the mold is removed by treatment with trichloroacetic acid.

Claim 32 (New): The method of Claim 1, wherein the mold is removed by treatment with dichloroacetic acid.

Claim 33 (New): The method of Claim 1, wherein the mold is removed by treatment with dimethyl acetoamide solution.